



Silicon Wafer Japan TC Chapter

Japan Standards Spring 2023 Meetings

Thursday, April 13, 2023

SEMI Japan office, Tokyo, Japan / WEB(Hybrid)

To be conducted by Official Virtual TC Chapter Meeting

<10:00 –noon JST>

AGENDA

	Time
1 Welcome/Call to Order	10:00
1.1 Introductions	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Agenda Review	
2 Review of Previous Meeting Minutes	
3 Ballot Review	
None	
4 Subcommittee & Task Force Reports	
4.1 International Advanced Wafer Geometry TF	
4.2 International / Japan Test Method TF	
4.3 International Advanced Surface Inspection TF	
4.4 International Polished Wafers TF	
4.5 International Epitaxial Wafers TF	
4.6 International Annealed Wafers TF	
4.7 International SOI Wafers TF	
4.8 International Terminology TF	
4.9 JA Shipping Box TF	
5 Liaison Report	
5.1 Europe TC Chapter	
5.2 North America TC Chapter	
5.3 GCS Report	
6 Staff Report	

7 Old Business**7.1 Project Period Review**

7.1.1 #5772 SNARF for: Revision of MF391-0310: Test Methods for Minority Carrier Diffusion Length in Extrinsic Semiconductors by Measurement of Steady-state Surface photovoltage

7.1.2 #6887 SNARF for: Revision of M51: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

7.2 5 Year Review Check

7.2.1 SEMI M51-1012: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

7.2.2 SEMI M60-1014: Test Method for Time Dependent Dielectric Breakdown Characteristics of SiO₂ Films for Si Wafer Evaluation

8 New Business

8.1 Proposal of New Activity

9 Action Item Review

9.1 Open Action Items

9.2 New Action Items

10 Next Meeting and Adjournment**12:00**

10.1 The next meeting is scheduled for <date> at <event/location>.